

Title (en)

Printed circuit board or card for direct chip attachment and fabrication thereof

Title (de)

Gedruckte Schaltungsplatte oder Schaltungskarte zur direkten Befestigung von Chips und ihre Herstellung

Title (fr)

Plaquette ou carte à circuit imprimé pour le montage direct de puces et sa fabrication

Publication

EP 0609774 B1 19970409 (EN)

Application

EP 94101191 A 19940127

Priority

US 1211193 A 19930201

Abstract (en)

[origin: US5685070A] A printed circuit board or card for direct chip attachment that includes at least one power core, at least one signal plane that is adjacent to the power core, and plated through holes for electrical connection is provided. In addition, a layer of dielectric material is adjacent the power core and a circuitized conductive layer is adjacent the dielectric material, followed by a layer of photosensitive dielectric material adjacent the conductive layer. Photodeveloped blind vias for subsequent connection to the power core and drilled blind vias for subsequent connection to the signal plane are provided. Also provided is process for fabricating the printed circuit board or card for direct chip attachment.

IPC 1-7

H05K 3/46; **H01L 23/538**

IPC 8 full level

H01L 23/12 (2006.01); **H01L 23/50** (2006.01); **H01L 23/538** (2006.01); **H05K 1/02** (2006.01); **H05K 1/11** (2006.01); **H05K 3/42** (2006.01); **H05K 3/46** (2006.01); **H05K 3/00** (2006.01)

CPC (source: EP US)

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DOCDB simple family (application)

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